

Land Grid Array Structures and Methods for Engineering Change

ABSTRACT OF THE DISCLOSURE:

A Land Grid Array structure is enhanced with a flex film interposer that not only provides a Land Grid Array (LGA) electrical connection between a Multi-Chip Module (MCM) and the next level of integration such as a system board, but also provides a reliable means to implement desired Engineering Change (EC) capability as well as a means for decoupling power to ground structure to minimize switching activity effects on the System. The invention as described can be implemented for EC repair, for Capacitive Decoupling or both.